

**METHOD AND RESULTING STRUCTURE FOR
MANUFACTURING SEMICONDUCTOR SUBSTRATE**

ABSTRACT OF THE DISCLOSURE

A method of manufacturing bonded substrates. The method includes providing a metallic substrate. The metal substrate has a predetermined thickness. The method also includes bonding a first thickness of compound semiconductor material overlying the metallic substrate and reducing a thickness of the first thickness of compound semiconductor material to a second thickness. The method includes forming one or more via structures through a portion of the second thickness of compound semiconductor material to a portion of the underlying metal substrate, whereupon the via structure electrically connects to the metal substrate.

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